

NTMFS4839N

Power MOSFET

30 V, 66 A, Single N-Channel, SO-8FL

Features

- Low $R_{DS(ON)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- These are Pb-Free Devices

Applications

- Refer to Application Note AND8195/D
- CPU Power Delivery
- DC-DC Converters

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

| Parameter | Symbol | Value | Unit | |
|--|--|--------------------------|------------------|---|
| Drain-to-Source Voltage | V_{DSS} | 30 | V | |
| Gate-to-Source Voltage | V_{GS} | ± 20 | V | |
| Continuous Drain Current $R_{\theta JA}$ (Note 1) | I_D | $T_A = 25^\circ\text{C}$ | 15 | A |
| | | $T_A = 85^\circ\text{C}$ | 11 | |
| Power Dissipation $R_{\theta JA}$ (Note 1) | P_D | $T_A = 25^\circ\text{C}$ | 2.17 | W |
| | | $T_A = 85^\circ\text{C}$ | | |
| Continuous Drain Current $R_{\theta JA}$ (Note 2) | I_D | $T_A = 25^\circ\text{C}$ | 9.5 | A |
| | | $T_A = 85^\circ\text{C}$ | 7.0 | |
| Power Dissipation $R_{\theta JA}$ (Note 2) | P_D | $T_A = 25^\circ\text{C}$ | 0.87 | W |
| | | $T_A = 85^\circ\text{C}$ | | |
| Continuous Drain Current $R_{\theta JC}$ (Note 1) | I_D | $T_C = 25^\circ\text{C}$ | 66 | A |
| | | $T_C = 85^\circ\text{C}$ | 48 | |
| Power Dissipation $R_{\theta JC}$ (Note 1) | P_D | $T_C = 25^\circ\text{C}$ | 41.7 | W |
| | | $T_C = 85^\circ\text{C}$ | | |
| Pulsed Drain Current | $T_A = 25^\circ\text{C}, t_p = 10 \mu\text{s}$ | I_{DM} | 132 | A |
| Operating Junction and Storage Temperature | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ | |
| Source Current (Body Diode) | I_S | 35 | A | |
| Drain to Source DV/DT | dV/dt | 6 | V/ns | |
| Single Pulse Drain-to-Source Avalanche Energy $T_J = 25^\circ\text{C}, V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_L = 19 \text{ A}_{pk}, L = 1.0 \text{ mH}, R_G = 25 \Omega$ | EAS | 180.5 | mJ | |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s) | T_L | 260 | $^\circ\text{C}$ | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

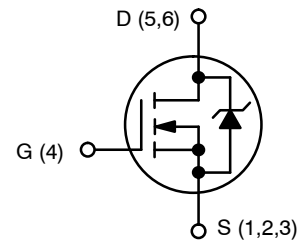
1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
 2. Surface-mounted on FR4 board using the minimum recommended pad size.
- *For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



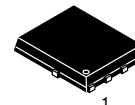
ON Semiconductor®

<http://onsemi.com>

| $V_{(BR)DSS}$ | $R_{DS(ON)}$ MAX | I_D MAX |
|---------------|------------------------|-----------|
| 30 V | 5.5 m Ω @ 10 V | 66 A |
| | 9.5 m Ω @ 4.5 V | |

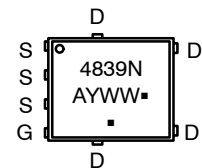


N-CHANNEL MOSFET



SO-8 FLAT LEAD
CASE 488AA
STYLE 1

MARKING DIAGRAM



- A = Assembly Location
 - Y = Year
 - WW = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|---------------------|-----------------------|
| NTMFS4839NT1G | SO-8FL (Pb-Free) | 1500 / Tape & Reel |
| NTMFS4839NT3G | SO-8FL (Pb-Free) | 5000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Junction-to-Case (Drain) | $R_{\theta JC}$ | 3.0 | °C/W |
| Junction-to-Ambient – Steady State (Note 3) | $R_{\theta JA}$ | 57.7 | |
| Junction-to-Ambient – Steady State (Note 4) | $R_{\theta JA}$ | 143.4 | |

3. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.

4. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|---|-------------------|---|---------------------------|----|-----------|---------------|
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 30 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS}/T_J$ | | | 25 | | mV/°C |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$ | $T_J = 25^\circ\text{C}$ | | 1 | μA |
| | | | $T_J = 125^\circ\text{C}$ | | 10 | |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |

ON CHARACTERISTICS (Note 5)

| | | | | | | | |
|--|------------------|---|---------------------|------|-----|-------|------------|
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$ | 1.5 | | 2.5 | V | |
| Negative Threshold Temperature Coefficient | $V_{GS(TH)}/T_J$ | | | 5.8 | | mV/°C | |
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V to } 11.5\text{ V}$ | $I_D = 30\text{ A}$ | | 4.5 | 5.5 | m Ω |
| | | | $I_D = 15\text{ A}$ | | 4.5 | | |
| | | $V_{GS} = 4.5\text{ V}$ | $I_D = 30\text{ A}$ | | 8.4 | 9.5 | |
| | | | $I_D = 15\text{ A}$ | | 8.4 | | |
| Forward Transconductance | g_{FS} | $V_{DS} = 15\text{ V}, I_D = 15\text{ A}$ | | 14.7 | | S | |

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | |
|------------------------------|--------------|---|--|------|----|----|
| Input Capacitance | C_{ISS} | $V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 12\text{ V}$ | | 1588 | | pF |
| Output Capacitance | C_{OSS} | | | 352 | | |
| Reverse Transfer Capacitance | C_{RSS} | | | 196 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 30\text{ A}$ | | 13 | 18 | nC |
| Threshold Gate Charge | $Q_{G(TH)}$ | | | 1.6 | | |
| Gate-to-Source Charge | Q_{GS} | | | 4.8 | | |
| Gate-to-Drain Charge | Q_{GD} | | | 5.8 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 11.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 30\text{ A}$ | | 28 | | nC |

SWITCHING CHARACTERISTICS (Note 6)

| | | | | | | |
|---------------------|--------------|--|--|-----|--|----|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 15\text{ A}, R_G = 3.0\ \Omega$ | | 12 | | ns |
| Rise Time | t_r | | | 29 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | | 18 | | |
| Fall Time | t_f | | | 7.0 | | |
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 11.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 15\text{ A}, R_G = 3.0\ \Omega$ | | 8.0 | | ns |
| Rise Time | t_r | | | 21 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | | 24 | | |
| Fall Time | t_f | | | 7.0 | | |

5. Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

6. Switching characteristics are independent of operating junction temperatures.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | |
|-------------------------|----------|--|---------------------------|------|-----|----|
| Forward Diode Voltage | V_{SD} | $V_{GS} = 0\text{ V}, I_S = 30\text{ A}$ | $T_J = 25^\circ\text{C}$ | 0.9 | 1.2 | V |
| | | | $T_J = 125^\circ\text{C}$ | 0.8 | | |
| Reverse Recovery Time | t_{RR} | $V_{GS} = 0\text{ V}, dI_S/dt = 100\text{ A}/\mu\text{s}, I_S = 30\text{ A}$ | | 22.2 | | ns |
| Charge Time | t_a | | | 12.5 | | |
| Discharge Time | t_b | | | 9.7 | | |
| Reverse Recovery Charge | Q_{RR} | | | 10.8 | | |

PACKAGE PARASITIC VALUES

| | | | | | | |
|-------------------|-------|--------------------------|--|-------|--|----------|
| Source Inductance | L_S | $T_A = 25^\circ\text{C}$ | | 0.93 | | nH |
| Drain Inductance | L_D | | | 0.005 | | nH |
| Gate Inductance | L_G | | | 1.84 | | nH |
| Gate Resistance | R_G | | | 3.3 | | Ω |

- Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
- Switching characteristics are independent of operating junction temperatures.

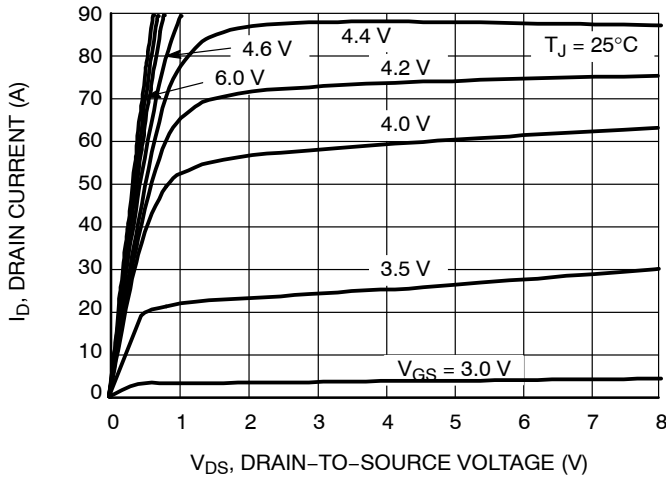


Figure 1. On-Region Characteristics

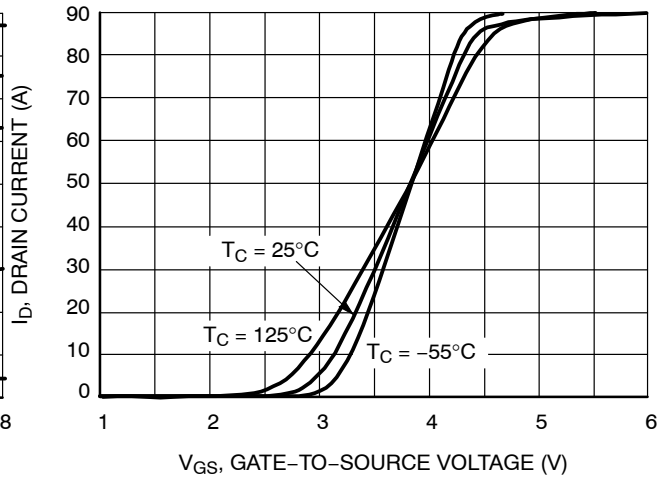


Figure 2. Transfer Characteristics

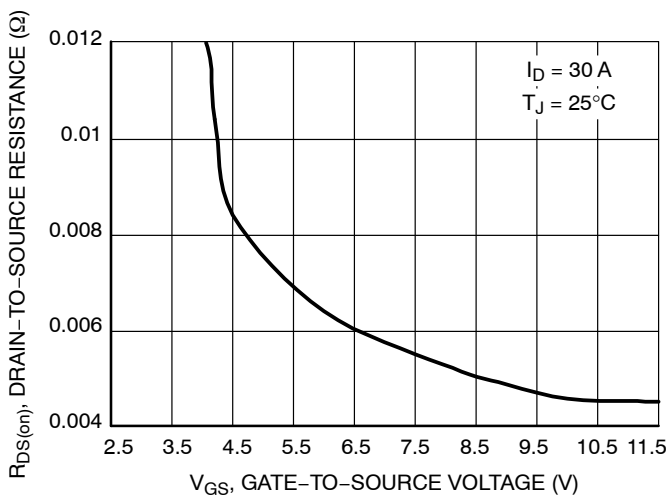


Figure 3. On-Resistance versus Gate-to-Source Voltage

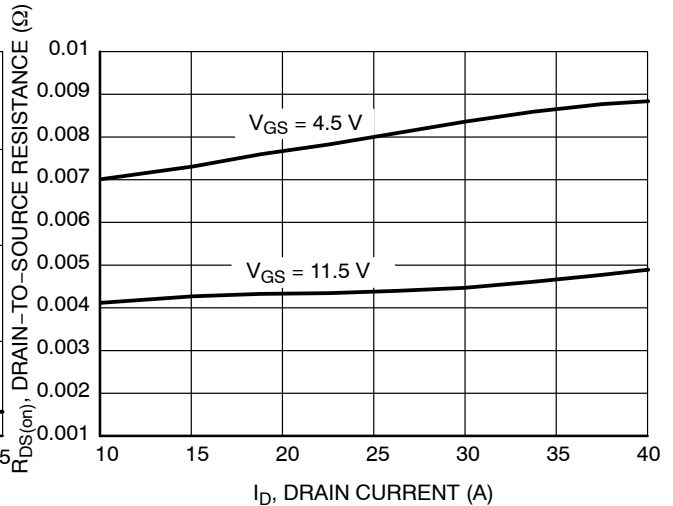


Figure 4. On-Resistance versus Drain Current and Temperature

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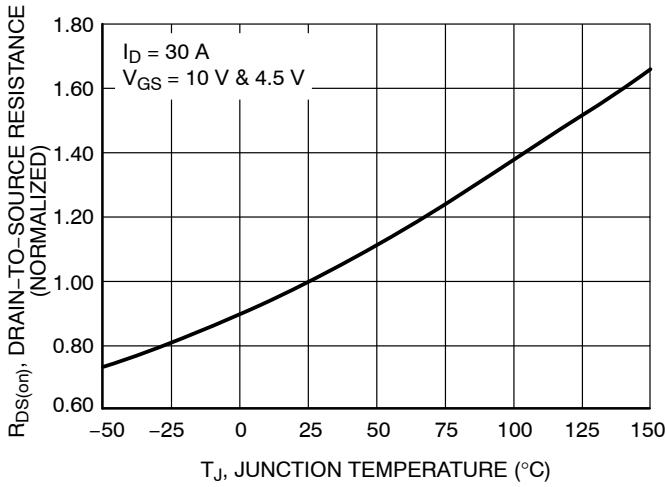


Figure 5. On-Resistance Variation with Temperature

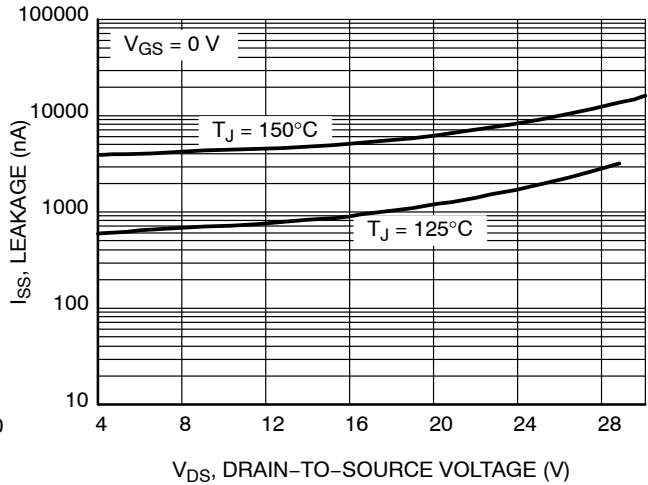


Figure 6. Drain-to-Source Leakage Current versus Voltage

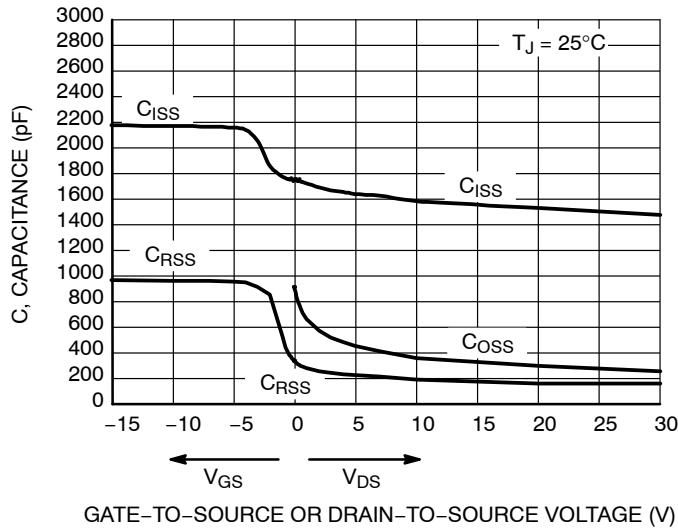


Figure 7. Capacitance Variation

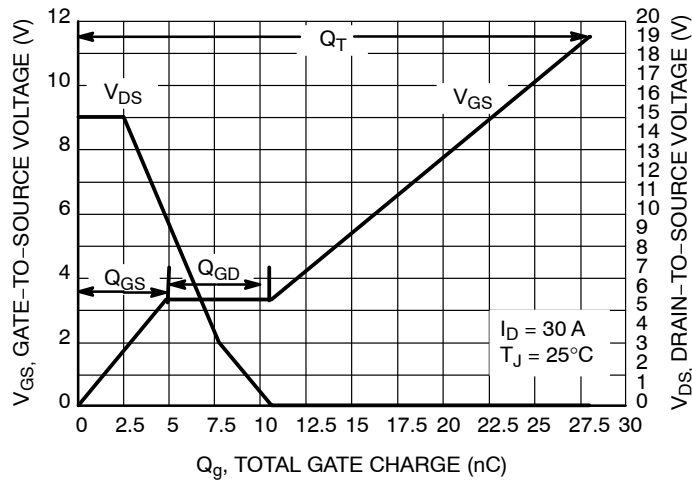


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Gate Charge

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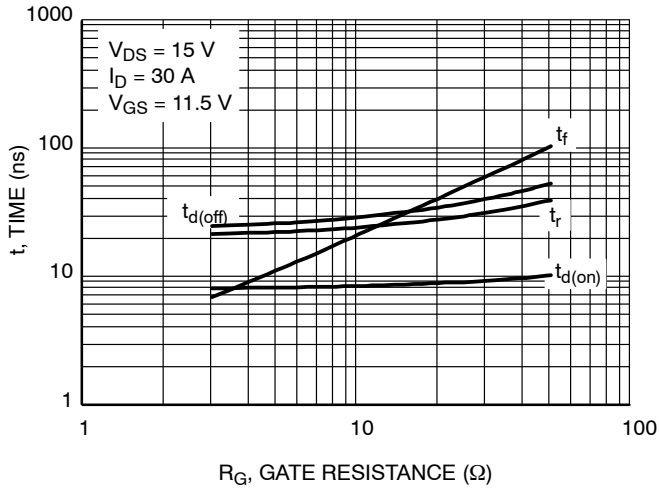


Figure 9. Resistive Switching Time Variation versus Gate Resistance

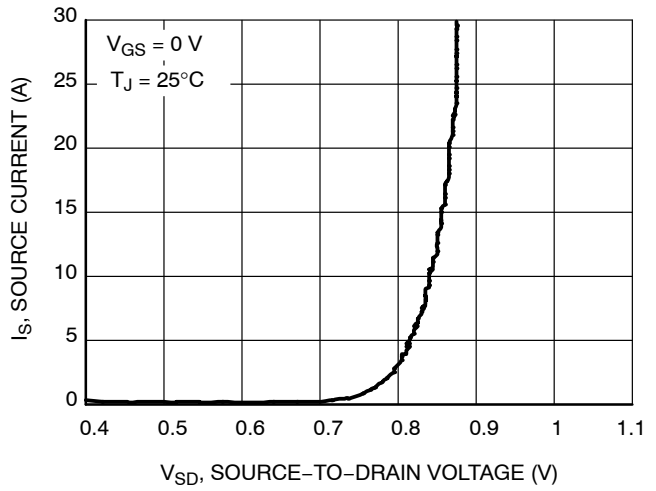


Figure 10. Diode Forward Voltage versus Current

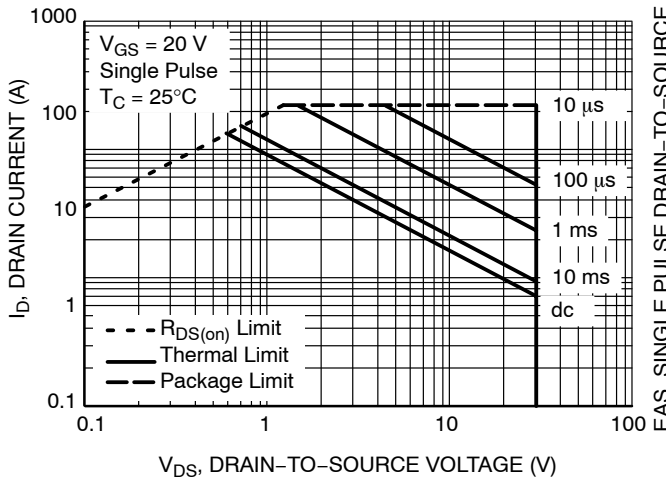


Figure 11. Maximum Rated Forward Biased Safe Operating Area

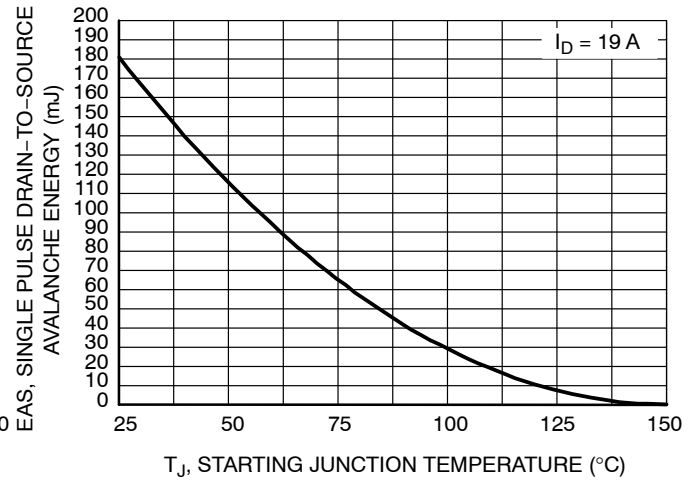
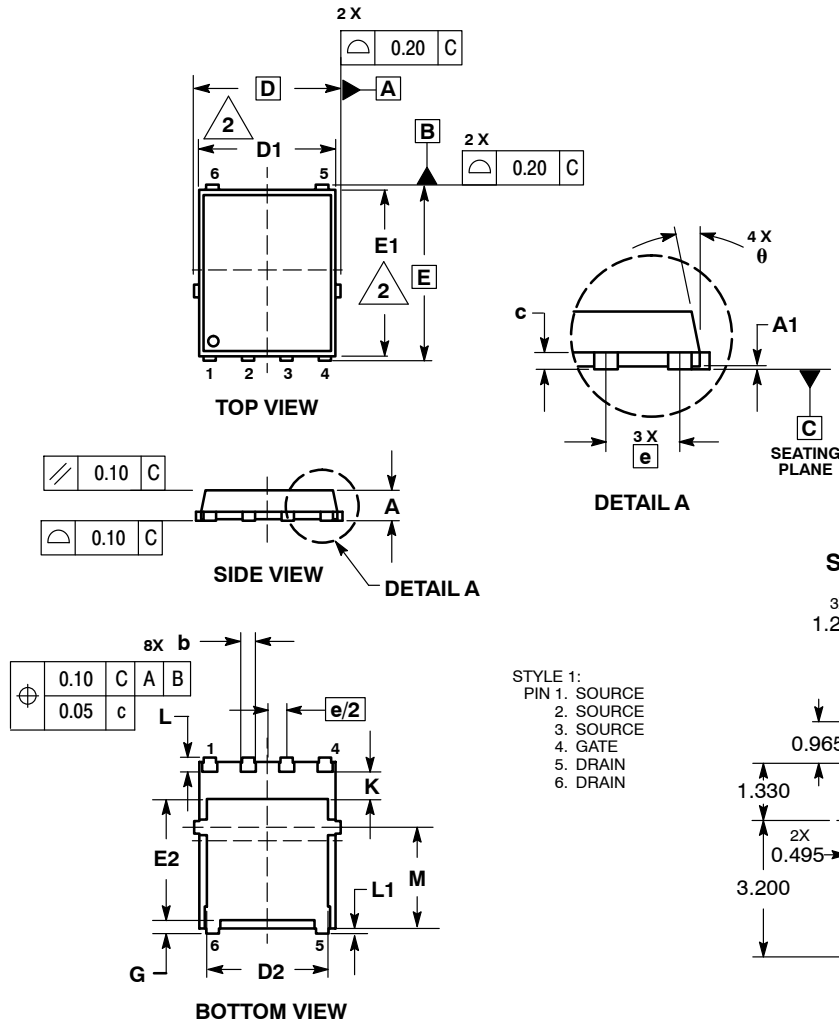


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

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PACKAGE DIMENSIONS

DFN6 5x6, 1.27P (S08 FL)
CASE 488AA-01
ISSUE C

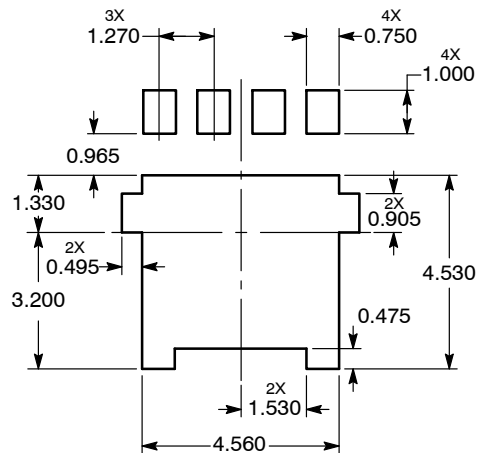


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN | NOM | MAX |
| A | 0.90 | 1.00 | 1.10 |
| A1 | 0.00 | --- | 0.05 |
| b | 0.33 | 0.41 | 0.51 |
| c | 0.23 | 0.28 | 0.33 |
| D | 5.15 BSC | | |
| D1 | 4.50 | 4.90 | 5.10 |
| D2 | 3.50 | --- | 4.22 |
| E | 6.15 BSC | | |
| E1 | 5.50 | 5.80 | 6.10 |
| E2 | 3.45 | --- | 4.30 |
| e | 1.27 BSC | | |
| G | 0.51 | 0.61 | 0.71 |
| K | 0.51 | --- | --- |
| L | 0.51 | 0.61 | 0.71 |
| L1 | 0.05 | 0.17 | 0.20 |
| M | 3.00 | 3.40 | 3.80 |
| θ | 0° | --- | 12° |

SOLDERING FOOTPRINT*



- STYLE 1:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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